



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-03-08
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	gregorio duro	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STPS20LCD80CR	HGI7*Z87S02L	A	993X	2024-03-08
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1500.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
Not Applicable	Not Applicable			
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM01009865	
Package designator	Package size	Number of instances	Shape	
SIP	10.20x9.15x4.50	3	Through-hole	
Comment	I2PAK			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		False
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		True
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		False
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		False
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		True
Exemption Id.	Description	
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 17th Nov 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			False
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			True
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.111	die - leadframe	741
Lead	2.113	soft solder	1409

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				False
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.113	Soft solder	1409
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				False
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Lead	1000 ppm	2.113	Soft solder	955244



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	False

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	False

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	True

QueryList : EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene, Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HG17'Z87S02L					
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.944	mg	supplier	die	Silicon(Si)	7440-21-3		3.751	mg	951064	2501
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.023	mg	5832	15
				supplier	metallisation	Gold(Au)	7440-57-5		0.022	mg	5578	15
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.043	mg	10903	29
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	1268	3
				supplier	metallisation	Tungsten(W)	7440-33-7		0.006	mg	1521	4
				supplier	passivation	Silicon oxide	7631-86-9		0.023	mg	5832	15
				supplier	polymer coating	Durimide	proprietary		0.071	mg	18002	47
				Leadframe	M-004 Copper and its alloys	840.695	mg	supplier	alloy	Copper(Cu)	7440-50-8	
supplier	alloy	Iron phosphide	26508-33-8						0.705	mg	839	470
supplier	alloy	Iron(Fe)	7439-89-6						0.386	mg	459	257
supplier	metallization	Nickel (Ni)	7440-02-0						1.068	mg	1270	712
supplier	metallization	Phosphorus (P)	7723-14-0						0.022	mg	26	15
Soft solder	Solder	2.212	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	2.113	mg	955244	1409
				supplier	solder	Tin(Sn)	7440-31-5		0.044	mg	19892	29
				supplier	solder	Silver(Ag)	7440-22-4		0.055	mg	24864	37
Bonding wires	M-003 Aluminum and its alloys	2.769	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.769	mg	1000000	1846
				Encapsulation	M-011 Other inorganic materials	569.947	mg	supplier	mold compound	Silica vitreous	60676-86-0	
supplier	mold compound	Epoxy Cresol Novolak	29690-82-2					88.342	mg	155000	58895	
supplier	mold compound	Quartz	14808-60-7					28.497	mg	49999	18998	
supplier	mold compound	Phenol resin	9003-35-4					34.197	mg	60000	22798	
supplier	mold compound	Metal hydroxide	21645-51-2					17.098	mg	29999	11399	
supplier	mold compound	Carbon black	1333-86-4					2.850	mg	5000	1900	
supplier	solder alloy	Tin (Sn)	7440-31-5					80.433	mg	1000000	53622	